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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: N. FUKASAWA et al.

Serial Number: 09/029,608

Filed: May 15, 1998

For: METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE,
SEMICONDUCTOR DEVICE, AND METHOD FOR MOUNTING THE DEVICE



Group Art Unit: 2814

Examiner: D. Graybill

AMENDMENT

Director of Patents and Trademarks
Washington, D.C. 20231

August 7, 2000

Sir:

In response to the Office Action dated May 8, 2000, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 1-12, 20-35, 37-40, 44-53, 65-69, 78, 86, 92-94 and 108 without prejudice or disclaimer.

Please amend claims 18, 42, 43, 57, 62, 71, 79, 90, 91, 97-100 and 102 as follows:

18. (Twice Amended) A semiconductor device comprising:

a semiconductor element having a surface on which protruding electrodes are formed;

and

a compressed resin layer which is formed on the surface of the semiconductor element

and seals at least a lateral surface of the protruding electrodes.